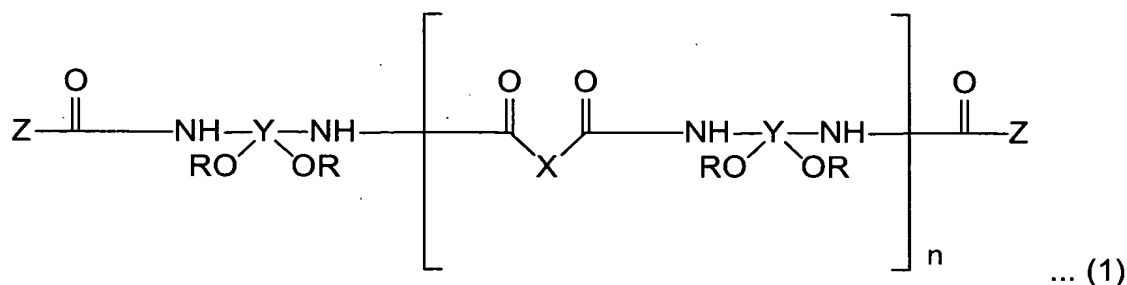


ABSTRACT OF THE DISCLOSURE

A photosensitive resin composition is disclosed that includes (A) a heat-resistant polymer of the general formula (1):



- 5 (where the symbols are as defined in the specification), (B) a photoreactive compound, and (C) a solvent. A relief pattern is formed from the composition by applying the composition to a support substrate and drying it to form a photosensitive resin film; exposing the dried film; developing the exposed film using an alkaline aqueous solution; and heating the developed photosensitive
- 10 resin film. Also disclosed is an electronic component that includes an electronic device having such a pattern.